

# Single-Slope Analog-to-Digital Conversion Technique Using MSP430™ MCUs



## Introduction

MSP430™ microcontrollers (MCUs) with an on-chip analog-to-digital (ADC) module are widely used in resistive elements measurement applications such as measuring the resistance of a thermistor in a thermostat, because resistance can be easily digitized by measuring the voltage across it. However, for MSP430 MCUs without an integrated ADC module, resistive elements still can be precisely measured with the on-chip comparator and timer using single-slope analog-to-digital (A/D) conversion technique.

The basic working principle of slope A/D resistance measurement is the charging and discharging of a known value capacitor ( $C_m$ ) through the resistor to be measured ( $R_{sense}$ ) and a reference resistor ( $R_{ref}$ ). By comparing the capacitor discharging time ( $t_{sense}$ ) through  $R_{sense}$  with the discharging time ( $t_{ref}$ ) through  $R_{ref}$ , the value of  $R_{sense}$  can be calculated with Equation 1.

$$\frac{R_{sense}}{t_{sense}} = \frac{R_{ref}}{t_{ref}} \quad (1)$$

For more details about slope A/D resistance measurement, see [Implementing An Ultralow-Power Thermostat With Slope A/D Conversion](#).

The implementation presented demonstrates the slope A/D conversion resistance measurement using the on-chip comparator and timer of the MSP430 MCUs. It has been optimized for lowest code size, fitting in a low-cost 0.5KB MSP430FR2000 microcontroller. To get started, [download project files and a code example](#) demonstrating this functionality.

## Implementation

Figure 1 shows the hardware configuration of a slope A/D resistance measurement implementation using the MSP430FR2000 MCU.

$R_{ref}$  is connected to P1.0 and  $R_{sense}$  is connected to P1.2. Capacitor  $C_m$  is connected to both resistors in series. eCOMP0 is used to monitor the voltage across  $C_m$  by connecting  $C_m$  to the positive input of eCOMP0. The built-in DAC is used to generate reference voltage ( $V_{CAREF}$ ) for comparator, and Timer\_B0 is configured as capture mode to capture signal from the output of eCOMP0.

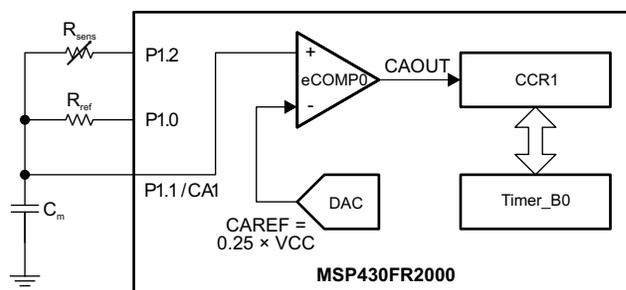
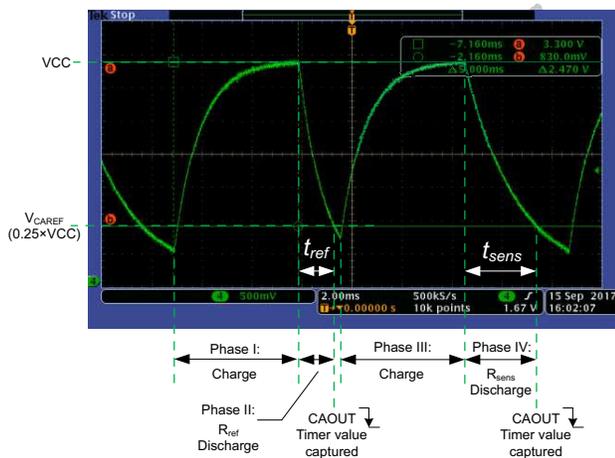


Figure 1. Measurement of Resistors

To measure the resistor value  $R_{sense}$ , capacitor  $C_m$  is first charged to the digital I/O high voltage ( $V_{OH} \approx V_{CC}$ ) by outputting a high on P1.0. After configuring the Time\_B0, the capacitor is discharged through  $R_{sense}$  through P1.2 by outputting a low level voltage. At the start of capacitor discharge, register TAR is cleared, and the timer is started. When the voltage across capacitor  $C_m$  reaches a comparator reference value  $V_{CAREF}$  of  $0.25 \times V_{CC}$ , the falling edge of the comparator output CAOUT causes the TAR value to be captured in register CCR1. This value is the discharge time interval  $t_{sense}$ . The process is repeated for the reference resistor  $R_{ref}$ , which is used to translate  $t_{sense}$  into the resistor value  $R_{sense}$ . More than one resistive element can be measured with this implementation. Additional elements are also connected to CA1 with available I/O pins and switched to high impedance when not being measured.

The software is designed around a main loop. In each loop,  $t_{ref}$  and  $t_{sense}$  are measured in sequence and then  $R_{sense}$  is calculated. Figure 2 shows voltage across  $C_m$  during each loop.



**Figure 2. Voltage at  $C_m$  During Resistance Measurement**

The MSP430 MCU is put to sleep while the capacitor is charging or discharging and the Timer\_B0 module is used. During charge phase, auxiliary clock (ACLK) is the source clock, and therefore the sleep mode low-power mode 3 (LPM3) is used. For discharge phase, subsystem master clock (SMCLK) is used (derived from the DCO) because of the higher frequency and greater slope ADC accuracy. Therefore, LPM0 is used in this case. Different timer modes are used in each case: Timer overflow interrupt wake the MCU from LPM3 and CCR1 capture interrupt wake the MCU from LPM0. In the interrupt service routines, the respective low-power mode bits are cleared, so that when the ISR is exited, the device remains active, returning operation to the place where it was put to sleep. Every time the main loop runs, the MSP430 device calculates the resistance value using the discharge times  $t_{sense}$  and  $t_{ref}$  as previously described.

Notice that the reference resistor is a fixed, precise 10-k $\Omega$  resistor. The value of resistor to be measured is in the range of 10 k $\Omega$ . Because both resistors use the same capacitor in the RC discharge measurement, assigning similar resistance values results in discharge times within the same range. This allows the implementation to use the same timer clock

configuration for each measurement and simple comparison of timer values. The reference resistor can be changed for different applications. For example, select a 1-k $\Omega$  reference resistor for PT1000 measurement.

In this design,  $C_m$  is 0.1  $\mu$ F and  $R_{ref}$  is 10 k $\Omega$ , so the time constant  $\tau = R_{ref} \times C_m = 1$  ms, and the time to charge  $C_m$  should be between  $5\tau$  (for 1% accuracy) and  $7\tau$  (for 0.1% accuracy). The value within this range depends on the accuracy required.

## Performance

High accuracy can be obtained with slope A/D resistance-measurement method. A 12-k $\Omega$  resistor was measured 100 times with a demonstration board, and the standard deviation of test results was 3.63, which means the accuracy is 0.03%. However, the tradeoff for high accuracy is that the sampling rate is limited due to the relatively long charge and discharge time. The sample rate in this demonstration is approximately 75 Hz, and there are additional code and execution cycles necessary to perform the measurement and calculation. The execution cost of the calculation comes in the form of one multiply and one divide per measurement. The code size of multiply and divide is 122 bytes from the CCS compiler.

This solution provides a slope A/D resistance-measurement solution with minimal external components using optimized software that fits in code-limited devices as small as 0.5KB.

## Device Recommendations

The device used in this example is part of the MSP430 Value Line Sensing portfolio of low-cost MCUs, designed for sensing and measurement applications. This example can be used with the devices shown in [Table 1](#) with minimal code changes. For more information on the entire Value Line Sensing MCU portfolio, visit [www.ti.com/MSP430ValueLine](http://www.ti.com/MSP430ValueLine).

**Table 1. Device Recommendations**

Part Number	Key Features
MSP430FR2000	0.5KB FRAM, 0.5KB RAM, eComp
MSP430FR2100	1KB FRAM, 0.5KB RAM, 10-bit ADC, eComp
MSP430FR2110	2KB FRAM, 1KB RAM, 10-bit ADC, eComp
MSP430FR2111	3.75KB FRAM, 1KB RAM, 10-bit ADC, eComp

## IMPORTANT NOTICE FOR TI DESIGN INFORMATION AND RESOURCES

Texas Instruments Incorporated ("TI") technical, application or other design advice, services or information, including, but not limited to, reference designs and materials relating to evaluation modules, (collectively, "TI Resources") are intended to assist designers who are developing applications that incorporate TI products; by downloading, accessing or using any particular TI Resource in any way, you (individually or, if you are acting on behalf of a company, your company) agree to use it solely for this purpose and subject to the terms of this Notice.

TI's provision of TI Resources does not expand or otherwise alter TI's applicable published warranties or warranty disclaimers for TI products, and no additional obligations or liabilities arise from TI providing such TI Resources. TI reserves the right to make corrections, enhancements, improvements and other changes to its TI Resources.

You understand and agree that you remain responsible for using your independent analysis, evaluation and judgment in designing your applications and that you have full and exclusive responsibility to assure the safety of your applications and compliance of your applications (and of all TI products used in or for your applications) with all applicable regulations, laws and other applicable requirements. You represent that, with respect to your applications, you have all the necessary expertise to create and implement safeguards that (1) anticipate dangerous consequences of failures, (2) monitor failures and their consequences, and (3) lessen the likelihood of failures that might cause harm and take appropriate actions. You agree that prior to using or distributing any applications that include TI products, you will thoroughly test such applications and the functionality of such TI products as used in such applications. TI has not conducted any testing other than that specifically described in the published documentation for a particular TI Resource.

You are authorized to use, copy and modify any individual TI Resource only in connection with the development of applications that include the TI product(s) identified in such TI Resource. NO OTHER LICENSE, EXPRESS OR IMPLIED, BY ESTOPPEL OR OTHERWISE TO ANY OTHER TI INTELLECTUAL PROPERTY RIGHT, AND NO LICENSE TO ANY TECHNOLOGY OR INTELLECTUAL PROPERTY RIGHT OF TI OR ANY THIRD PARTY IS GRANTED HEREIN, including but not limited to any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information regarding or referencing third-party products or services does not constitute a license to use such products or services, or a warranty or endorsement thereof. Use of TI Resources may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

TI RESOURCES ARE PROVIDED "AS IS" AND WITH ALL FAULTS. TI DISCLAIMS ALL OTHER WARRANTIES OR REPRESENTATIONS, EXPRESS OR IMPLIED, REGARDING TI RESOURCES OR USE THEREOF, INCLUDING BUT NOT LIMITED TO ACCURACY OR COMPLETENESS, TITLE, ANY EPIDEMIC FAILURE WARRANTY AND ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE, AND NON-INFRINGEMENT OF ANY THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

TI SHALL NOT BE LIABLE FOR AND SHALL NOT DEFEND OR INDEMNIFY YOU AGAINST ANY CLAIM, INCLUDING BUT NOT LIMITED TO ANY INFRINGEMENT CLAIM THAT RELATES TO OR IS BASED ON ANY COMBINATION OF PRODUCTS EVEN IF DESCRIBED IN TI RESOURCES OR OTHERWISE. IN NO EVENT SHALL TI BE LIABLE FOR ANY ACTUAL, DIRECT, SPECIAL, COLLATERAL, INDIRECT, PUNITIVE, INCIDENTAL, CONSEQUENTIAL OR EXEMPLARY DAMAGES IN CONNECTION WITH OR ARISING OUT OF TI RESOURCES OR USE THEREOF, AND REGARDLESS OF WHETHER TI HAS BEEN ADVISED OF THE POSSIBILITY OF SUCH DAMAGES.

You agree to fully indemnify TI and its representatives against any damages, costs, losses, and/or liabilities arising out of your non-compliance with the terms and provisions of this Notice.

This Notice applies to TI Resources. Additional terms apply to the use and purchase of certain types of materials, TI products and services. These include; without limitation, TI's standard terms for semiconductor products (<http://www.ti.com/sc/docs/stdterms.htm>), [evaluation modules](#), and [samples](http://www.ti.com/sc/docs/sampterm.htm) (<http://www.ti.com/sc/docs/sampterm.htm>).

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2017, Texas Instruments Incorporated